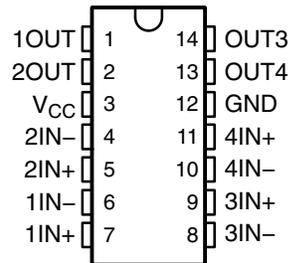


# LM2901-Q1, LM2901AV-Q1, LM2901V-Q1 QUADRUPLE DIFFERENTIAL COMPARATOR

SLCS142D – DECEMBER 2003 – REVISED APRIL 2008

- Qualified for Automotive Applications
- Single Supply or Dual Supplies
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.8 mA Typ
- Low Input Bias Current . . . 25 nA Typ
- Low Input Offset Current . . . 2 nA Typ
- Low Input Offset Voltage . . . 2 mV Typ
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . .  $\pm 36$  V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS
- For Single Version in SOT23-5, See TL331

D OR PW PACKAGE  
(TOP VIEW)



## description/ordering information

This device consists of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies is possible, as long as the difference between the two supplies is 2 V to 36 V, and  $V_{CC}$  is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

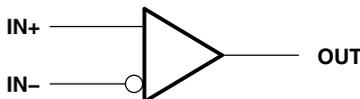
## ORDERING INFORMATION†

$T_A$	$V_{IOmax}$ AT 25°C	MAX $V_{CC}$	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	7 mV	30 V	SOIC (D)	Reel of 2500	LM2901QDRQ1	2901Q1
			TSSOP (PW)	Reel of 2000	LM2901QPWRQ1	2901Q1
-40°C to 125°C	7 mV	32 V	SOIC (D)	Reel of 2500	LM2901VQDRQ1	2901VQ1
			TSSOP (PW)	Reel of 2000	LM2901VQPWRQ1	2901VQ1
-40°C to 125°C	2 mV	32 V	SOIC (D)	Reel of 2500	LM2901AVQDRQ1	2901AVQ
			TSSOP (PW)	Reel of 2000	LM2901AVQPWRQ1	2901AVQ

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

## symbol (each comparator)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

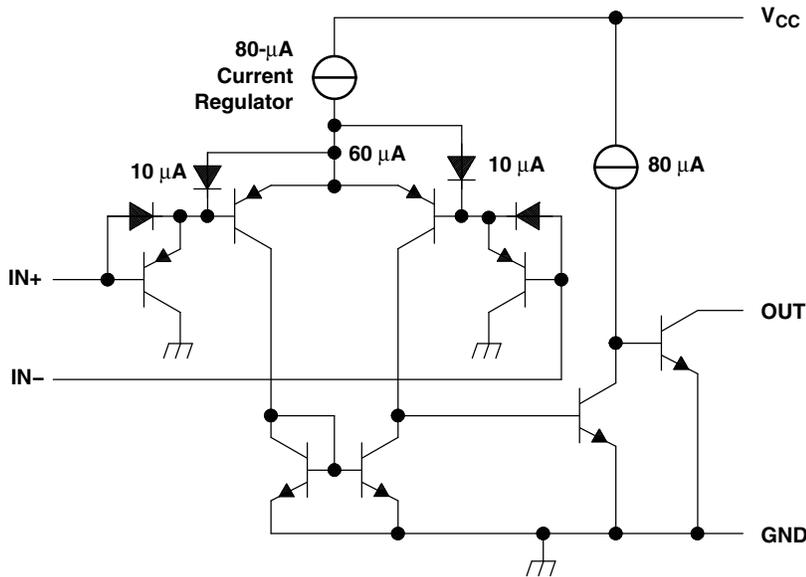
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# LM2901-Q1, LM2901AV-Q1, LM2901V-Q1 QUADRUPLE DIFFERENTIAL COMPARATOR

SLCS142D – DECEMBER 2003 – REVISED APRIL 2008

## schematic (each comparator)



All current values shown are nominal.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, $V_{CC}$ (see Note 1)	36 V
Differential input voltage, $V_{ID}$ (see Note 2)	$\pm 36$ V
Input voltage range, $V_I$ (either input)	-0.3 V to 36 V
Output voltage, $V_O$	36 V
Output current, $I_O$	20 mA
Duration of output short circuit to ground (see Note 3)	Unlimited
Package thermal impedance, $\theta_{JA}$ (see Notes 4 and 5):	
D package	86°C/W
PW package	113°C/W
Operating virtual junction temperature, $T_J$	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values, except differential voltages, are with respect to network ground.

2. Differential voltages are at IN+ with respect to IN-.

3. Short circuits from outputs to  $V_{CC}$  can cause excessive heating and eventual destruction.

4. Maximum power dissipation is a function of  $T_J(\max)$ ,  $\theta_{JA}$ , and  $T_A$ . The maximum allowable power dissipation at any allowable ambient temperature is  $P_D = (T_J(\max) - T_A)/\theta_{JA}$ . Operating at the absolute maximum  $T_J$  of 150°C can affect reliability.

5. The package thermal impedance is calculated in accordance with JESD 51-7.



**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM2901AVQDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	<a href="#">Samples</a>
LM2901AVQDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	<a href="#">Samples</a>
LM2901AVQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	<a href="#">Samples</a>
LM2901AVQPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901AVQ	<a href="#">Samples</a>
LM2901QDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	<a href="#">Samples</a>
LM2901QDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	<a href="#">Samples</a>
LM2901QPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	<a href="#">Samples</a>
LM2901QPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901Q1	<a href="#">Samples</a>
LM2901VQDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ1	<a href="#">Samples</a>
LM2901VQDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ1	<a href="#">Samples</a>
LM2901VQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ	<a href="#">Samples</a>
LM2901VQPWRQ1	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2901VQ	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

<sup>(4)</sup> Only one of markings shown within the brackets will appear on the physical device.

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**OTHER QUALIFIED VERSIONS OF LM2901-Q1, LM2901AV-Q1, LM2901V-Q1 :**

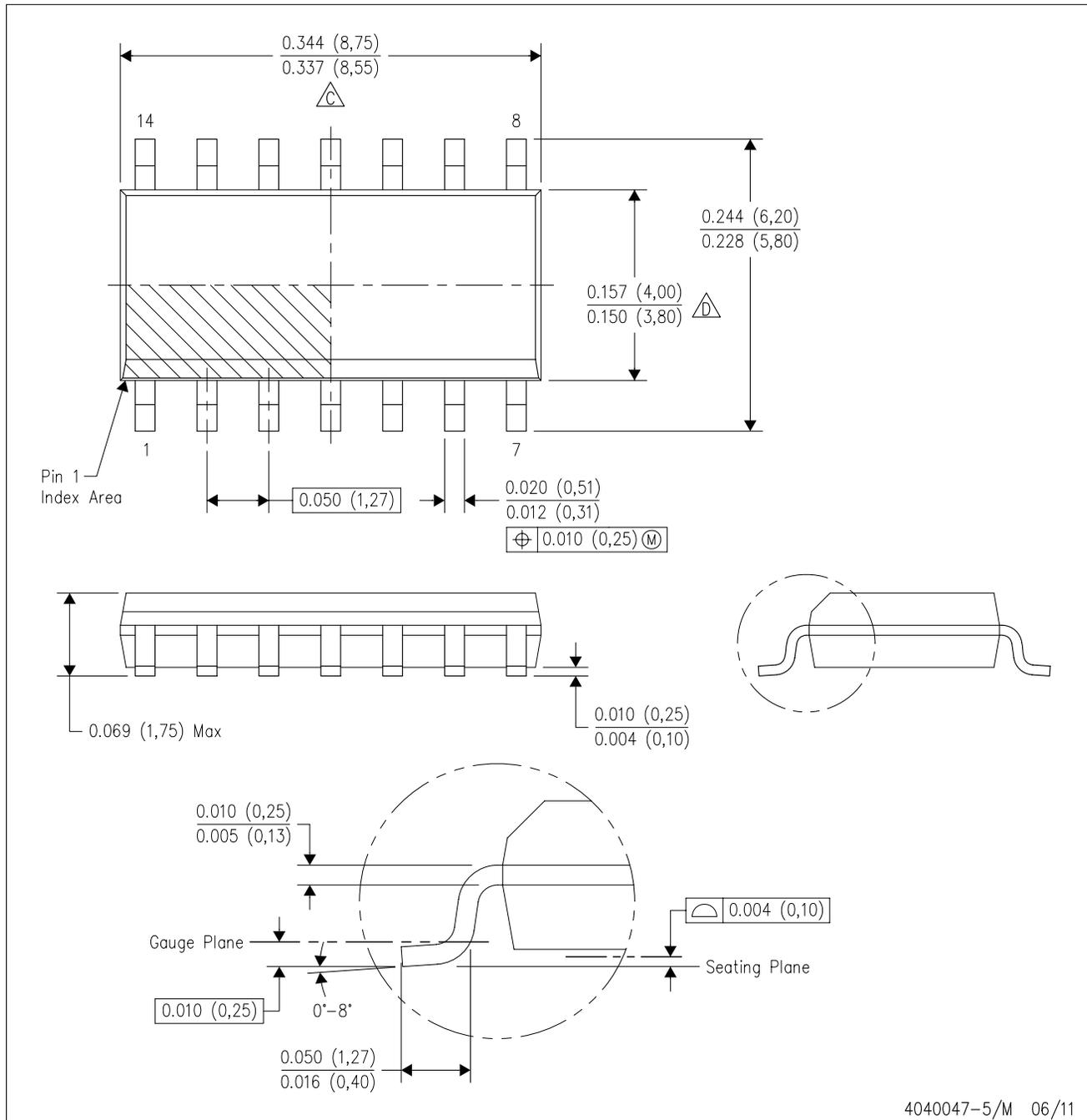
- Catalog: [LM2901](#), [LM2901AV](#), [LM2901V](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

D (R-PDSO-G14)

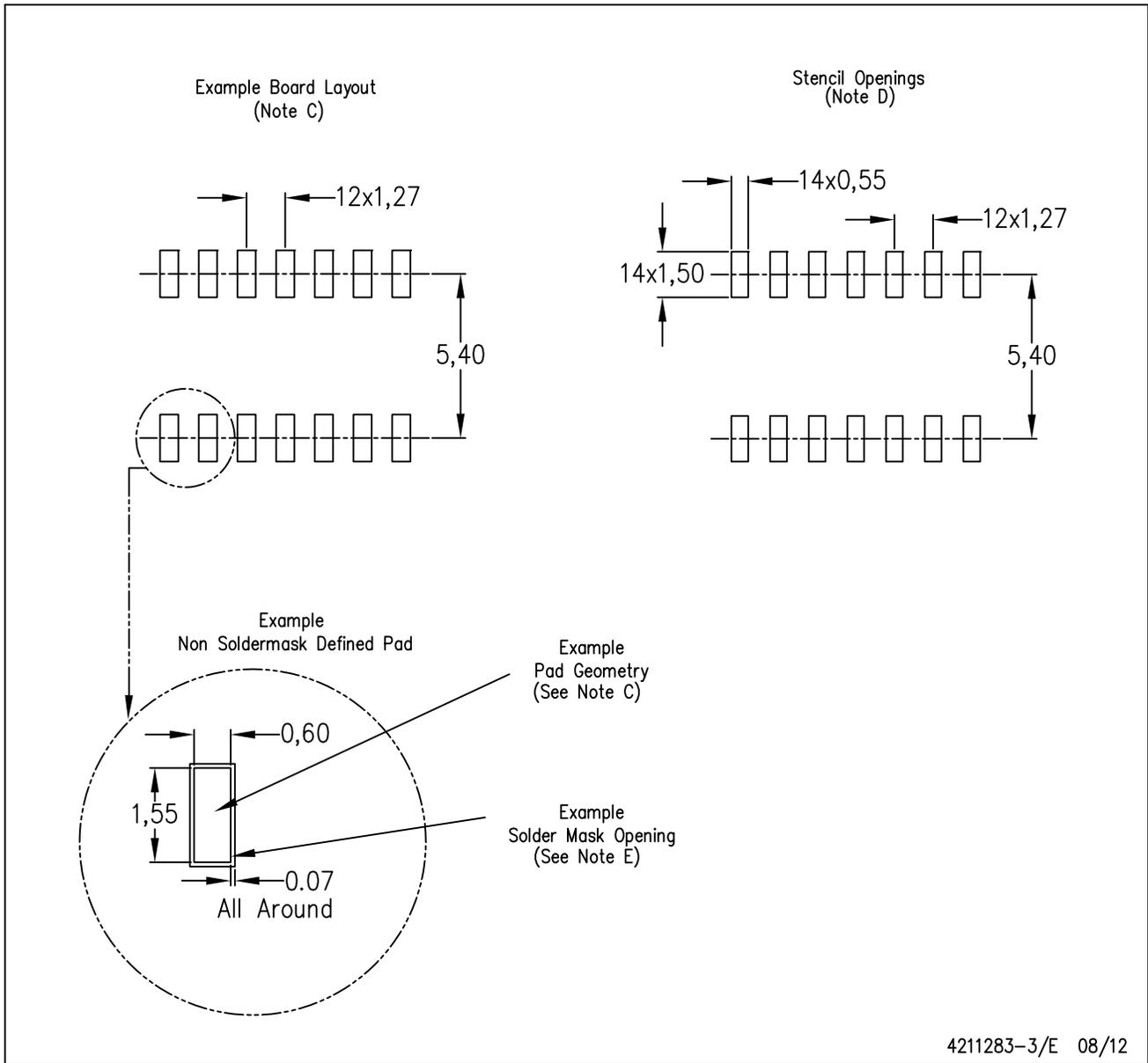
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
  -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
  - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE

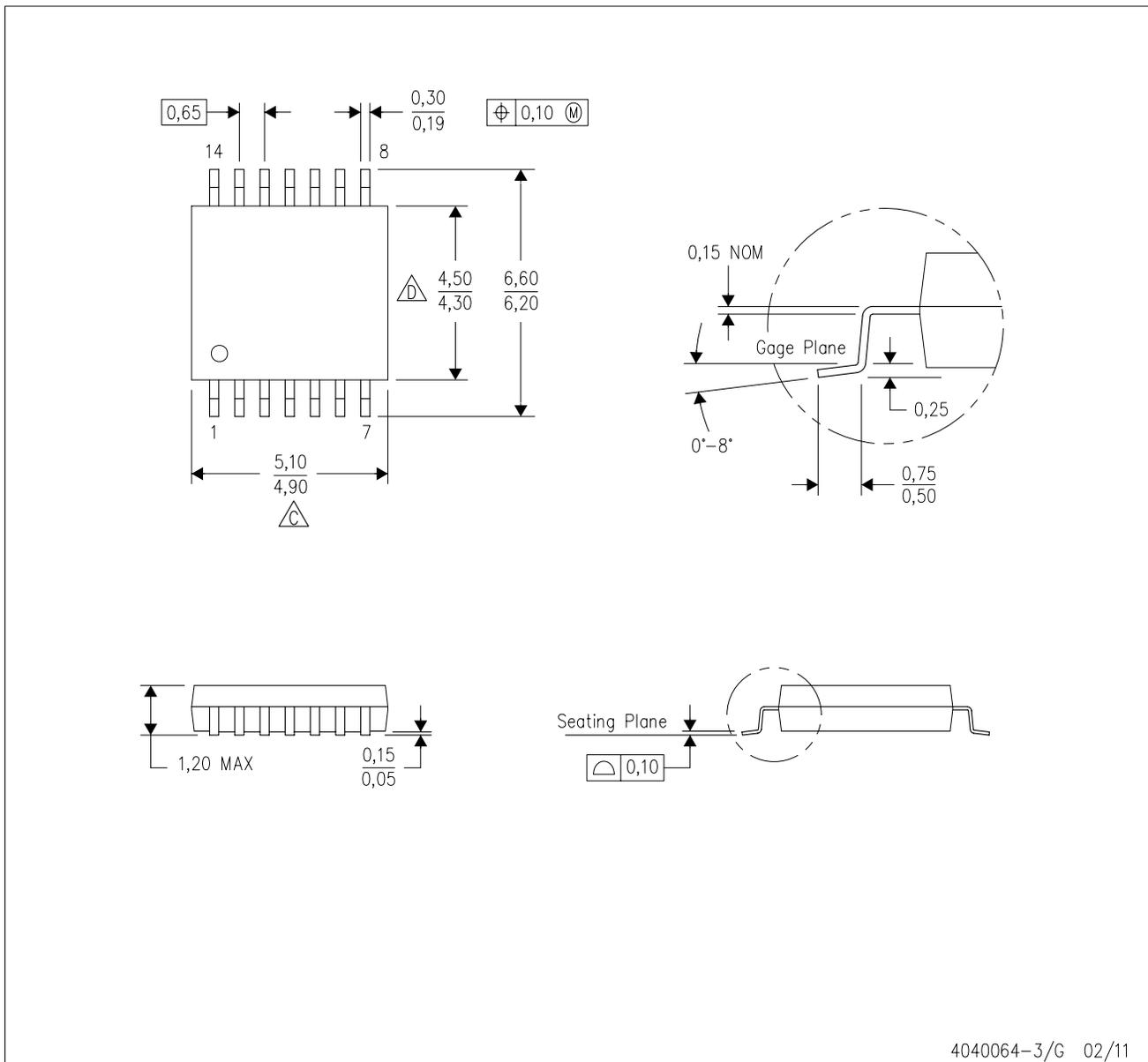


4211283-3/E 08/12

- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Publication IPC-7351 is recommended for alternate designs.
  - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

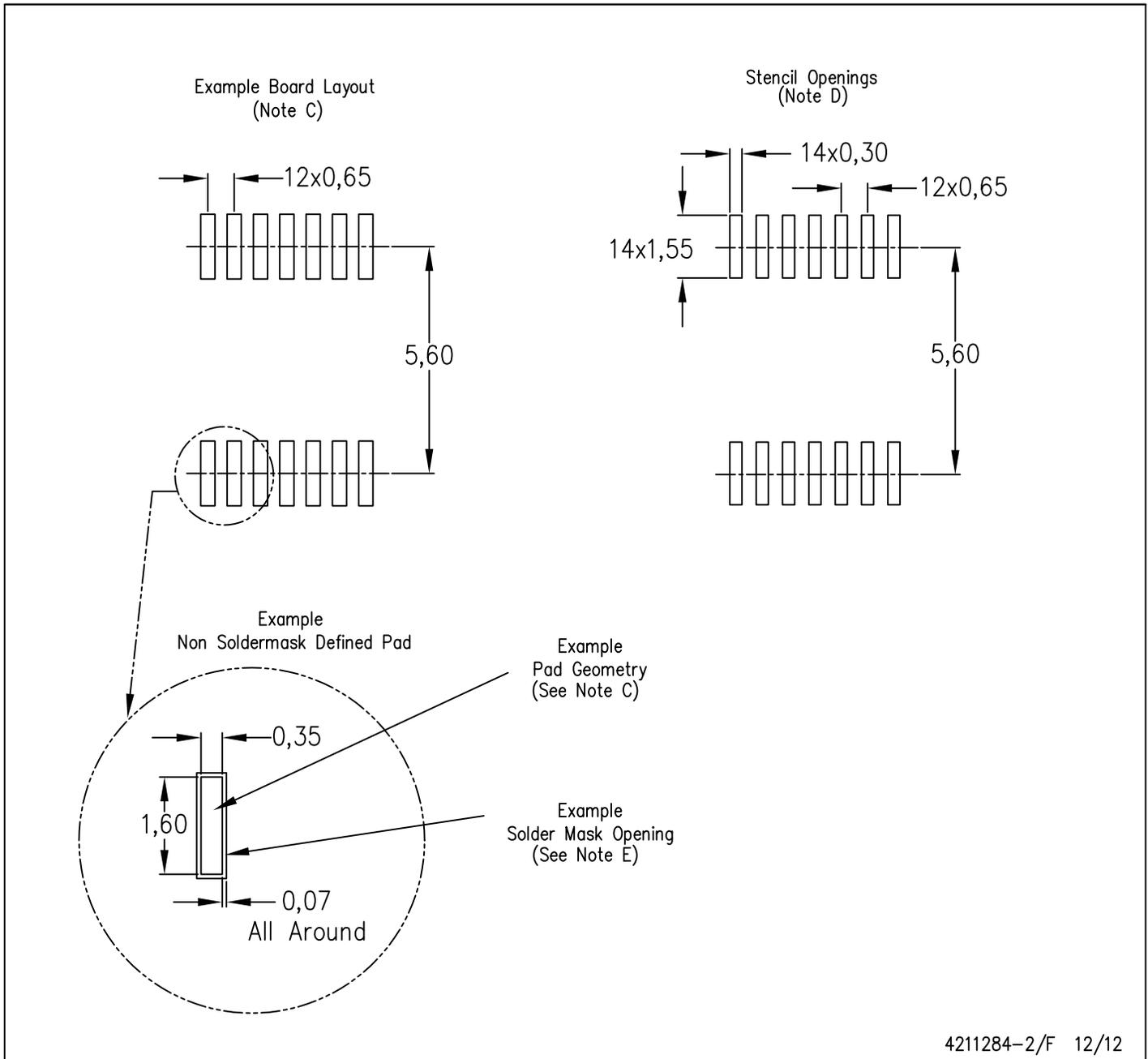


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
  - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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